

WHAT WE CLAIM IS:

1. A semiconductor device comprising:

a substrate;

5 a semiconductor chip having one surface bonded to a surface
of the substrate; and

a warp preventing sheet bonded to the other surface of
the semiconductor chip.

10 2. A semiconductor device according to Claim 1, wherein
the warp preventing sheet has a coefficient of elasticity
substantially equal to that of the substrate.

15 3. A semiconductor device according to Claim 1, wherein
the warp preventing sheet has a coefficient of thermal expansion
substantially equal to the of the substrate.

20 4. A semiconductor device according to Claim 1, wherein
a base of the warp preventing sheet is made of material identical
with that of a base of the substrate.

5. A semiconductor device according to Claim 1, wherein
a base of each of the substrate and the warp preventing sheet
is a polyimide resin.

5 7. A semiconductor device according to Claim 1, wherein
the semiconductor device is a thin semiconductor device of a
chip-size package type.